

In re: Byung-jun Park
Serial No.: To Be Assigned
Filed: Currently Herewith
Page 2 of 6

In the Specification:

At page 1, line 2, please change the title as follows:

INTEGRATED CIRCUITS HAVING SELF-ALIGNED METAL CONTACT
~~STRUCTURES AND METHODS OF FABRICATING SAME~~

On page 1, after the title, please insert a section entitled "Related Application" as follows:

Related Applications

The present application is a divisional of United States Application Serial No. 10/172,760, filed June 14, 2002, entitled *Method of Fabricating Integrated Circuit Having Self-Aligned Metal Contact Structure*, the disclosure of which is hereby incorporated herein by reference.